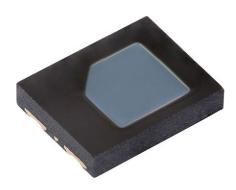


Ambient Light Sensor



DESCRIPTION

VEMD5510CF is a high speed and high sensitive PIN photodiode. It is a low profile surface-mount device (SMD) including the chip with a 7.5 mm² sensitive area detecting visible light much like the human eye. The diode has its peak sensitivity at 540 nm and a low capacitance.

FEATURES

- Package type: surface-mount
- · Package form: top view
- Dimensions (L x W x H in mm): 5 x 4 x 0.9
- Radiant sensitive area (in mm²): 7.5
- · Supression filter for infrared radiation
- Fast response times
- Angle of half sensitivity: $\varphi = \pm 65^{\circ}$
- Floor life: 72 h, MSL 4, according to J-STD-020
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





RoHS

FREE GREEN

APPLICATIONS

- Wearables
- · Optical heart rate monitoring
- · Ambient light sensors

PRODUCT SUMMARY				
COMPONENT	I _{ra} (μΑ)	φ (°)	λ _{0.5} (nm)	
VEMD5510CF	0.25	± 65	440 to 620	

Note

· Test conditions see table "Basic Characteristics"

ORDERING INFORMATION				
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM	
VEMD5510CF	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Top view	
VEMD5510CF-GS15	Tape and reel	MOQ: 5000 pcs, 5000 pcs/reel	Top view	

Note

• MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_{R}	20	V
Power dissipation	T _{amb} ≤ 25 °C	P_V	215	mW
Junction temperature		Tj	110	°C
Operating temperature range		T _{amb}	-40 to +100	°C
Storage temperature range		T _{stg}	-40 to +100	°C
Soldering temperature	According to reflow solder profile Fig. 8	T_{sd}	260	°C
Thermal resistance junction-to-ambient		R _{thJA}	350	K/W
ESD safety HBM	± 2000 V, 1.5 kΩ, 100 pF, 3 pulses	ESD _{HBM}	≥2	kV



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BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I _F = 50 mA	V _F	=	0.9	1.3	V
Breakdown voltage	I _R = 100 μA, E = 0	V _(BR)	20	-	=	V
Reverse dark current	V _R = 10 V, E = 0	I _{ro}	=	0.2	10	nA
Diode capacitance	$V_R = 0 V, f = 1 MHz, E = 0$	C _D	=	80	=	pF
	V _R = 3 V, f = 1 MHz, E = 0	C _D	=	30	40	pF
Open circuit voltage	E _V = 100 lx, CIE illuminant A	Vo	=	210	=	mV
Temperature coefficient of Vo	E _V = 100 lx, CIE illuminant A	TK _{Vo}	=	-2.3	=	mV/K
Short circuit current	E _V = 100 lx, CIE illuminant A	l _k	-	0.25	-	μA
Reverse light current	$E_e = 0.2 \text{ mW/cm}^2$, $\lambda = 525 \text{ nm}$, $V_R = 5 \text{ V}$	I _{ra}	1.35	2.1	3.05	μΑ
	$E_V = 100 Ix$, CIE illuminant A, $V_R = 5 V$	I _{ra}	0.16	0.25	0.39	μΑ
Angle of half sensitivity		φ	-	± 65	-	0
Wavelength of peak sensitivity		λ_{p}	-	540	-	nm
Range of spectral bandwidth		λ _{0.5}	=	440 to 620	=	nm
Rise time	$V_R = 5 \text{ V}, R_L = 50 \ \Omega, \lambda = 525 \text{ nm}$	t _r	=	40	=	ns
Fall time	$V_R = 5 \text{ V}, R_L = 50 \ \Omega, \lambda = 525 \text{ nm}$	t _f	=	30	=	ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

Basic characteristics graphs to be extended to 110 °C ambient temperatures where applicable.

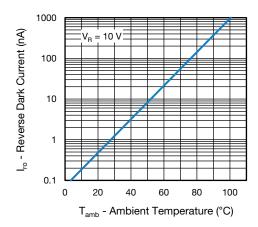


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

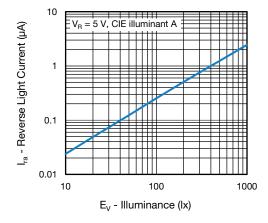


Fig. 2 - Reverse Light Current vs. Irradiance



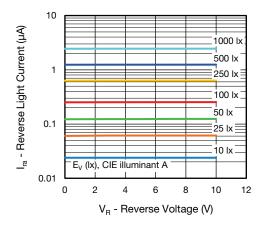


Fig. 3 - Reverse Light Current vs. Reverse Voltage

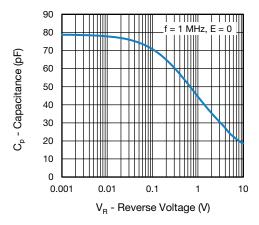


Fig. 4 - Diode Capacitance vs. Reverse Voltage

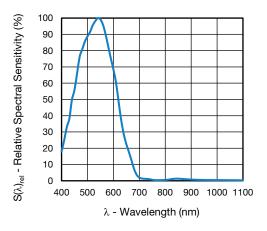


Fig. 5 - Relative Spectral Sensitivity vs. Wavelength

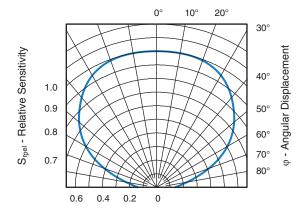
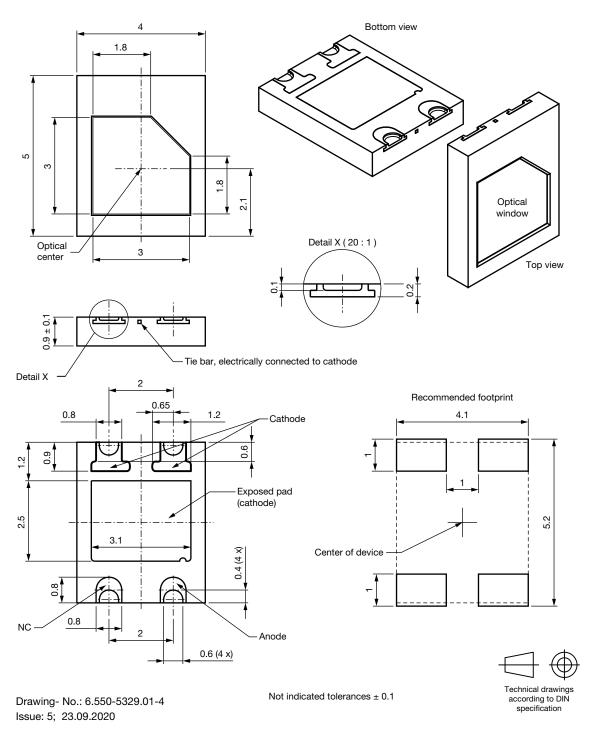
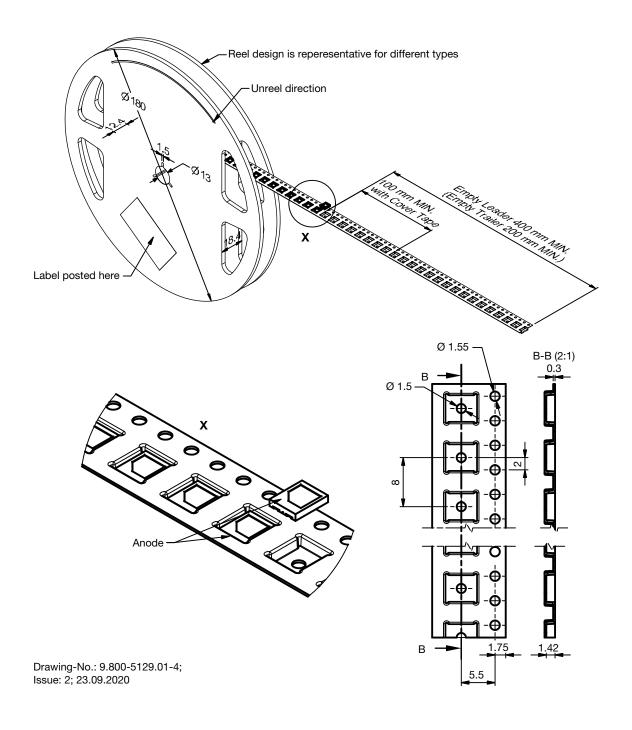


Fig. 6 - Relative Sensitivity vs. Angular Displacement

PACKAGE DIMENSIONS in millimeters



TAPE AND REEL DIMENSIONS in millimeters





SOLDER PROFILE

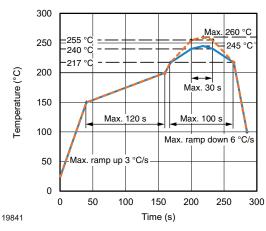


Fig. 7 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020D

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 4

Floor life: 72 h

Conditions: T_{amb} < 30 °C, RH < 60 %

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or recommended conditions:

192 h at 40 °C (+ 5 °C), RH < 5 %

or

96 h at 60 °C (+ 5 °C), RH < 5 %.



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